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Doc. No. ESEC-P32US-D1

CP 3729/18

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Schindler, S.
SERIAL NO.: 09/726,736
FILING DATE: November 29, 2000
TITLE: SEMICONDUCTOR MOUNTING APPARATUS WITH A CHIP GRIPPER TRAVELING BACK AND FORTH
EXAMINER: Chang, R. K.
ART UNIT: 3729

CERTIFICATE OF MAILING

I hereby certify that this paper is being deposited with the United States Postal Service as First Class
Mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231, on
the date printed below:

Date: 8/2/02

Name: Diane Morse
Diane Morse

COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

TRANSMITTAL LETTER

Enclosed for filing are the following documents:

1. Amendment.

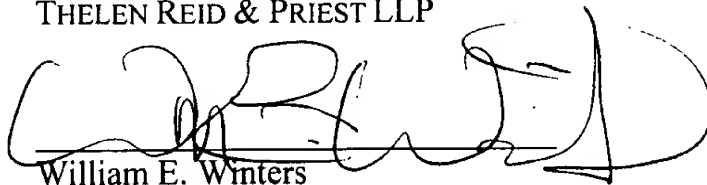
Enclosed is our check in the amount of \$156.00 as required for the filing fee,
calculated as follows:

| | |
|---|-----------|
| 1 Additional Independent Claim @ \$84.00: | \$ 84.00 |
| 3 Additional Claims @ \$18.00: | \$ 72.00 |
| Total Filing Fee: | \$ 156.00 |

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The Commissioner is hereby authorized to charge our Deposit Account No. 50-1698 for any fees for filing the above-noted document, including any fees required under 37 CFR § 1.136 for any necessary Extension of Time to make the filing of the attached document timely. A duplicate copy of this page is enclosed.

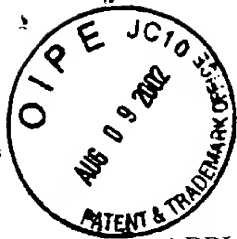
Respectfully submitted,
THELEN REID & PRIEST LLP

A handwritten signature in black ink, appearing to read 'W. E. Winters', written over a horizontal line.

William E. Winters
Reg. No. 42,232

Dated: August 2, 2002

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Assistant Commissioner for Patents
Washington, D.C. 20231

AMENDMENT

In response to the Office Action dated May 2, 2002, please amend the above-identified
application as follows.

IN THE CLAIMS:

Please amend claims 15-36 as follows:

15. (Once Amended) An apparatus used as a component of a die bonder for placing a
semiconductor chip on a substrate, comprising:

B1
Sub 37
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